Variant: 001
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TID #: TIDA-03042

TIDA-03042 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C1	1	1uF	GRM219R71E105KA88D	MuRata	CAP, CERM, 1 µF, 25 V, +/- 10%, X7R, 0805	0805
2	C2	1	10uF	C2012X5R1E106K125AB	TDK	CAP, CERM, 10uF, 25V, +/-10%, X5R, 0805	0805
3	C3	1	4.7uF	GRM188R61C475KAAJ	MuRata	CAP, CERM, 4.7uF, 16V, +/-10%, X5R, 0603	0603
4	C4	1	0.047uF	GRM155R71E473KA88D	MuRata	CAP, CERM, 0.047uF, 25V, +/-10%, X7R, 0402	0402
5	C5	1	22uF	C2012X5R1C226M125AC	TDK	CAP, CERM, 22 µF, 16 V, +/- 20%, X5R, 0805	0805
6	C7	1	10uF	GRM21BR71A106KE51L	MuRata	CAP, CERM, 10 µF, 10 V, +/- 10%, X7R, 0805	0805
7	C8	1	1000pF	GRM188R71E102KA01D	MuRata	CAP, CERM, 1000 pF, 25 V, +/- 10%, X7R, 0603	0603
8	J1, J3, J4	3	2x1	1727010	Phoenix Contact	Conn Term Block, 2POS, 3.81mm, TH	2POS Terminal Block
9	J8	1		22-05-3041	Molex	Header, 100mil, 4x1, R/A, TH	4x1 R/A Header
10	JP4	1		PEC03SAAN	Sullins Connector Solutions	Header, 100mil, 3x1, Tin plated, TH	Header, 3 PIN, 100mil, Tin
11	JP6, JP7	2		PEC02SAAN	Sullins Connector Solutions	Header, 100mil, 2x1, Tin plated, TH	Header, 2 PIN, 100mil, Tin
12	L1	1	1uH	74479275210	Wurth Elektronik	Inductor, Shielded, 1 µH, 1.8 A, 0.078 ohm, SMD	2x1.25mm
13	R2, R5, R6, R8, R14, R15	6	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0k ohm, 1%, 0.063W, 0402	0402
14	R18	1	232	CRCW0402232RFKED	Vishay-Dale	RES, 232, 1%, 0.063 W, 0402	0402
15	R21, R22	2	2.21k	CRCW04022K21FKED	Vishay-Dale	RES, 2.21k ohm, 1%, 0.063W, 0402	0402
16	SH-J4, SH-J6, SH-J7	3	1x2	SNT-100-BK-G	Samtec	Shunt, 100mil, Gold plated, Black	Shunt
17	U1	1		BQ25898YFFR	Texas Instruments	I2C Controlled 4A Single Cell NVDC Power Path Management with MaxChargeTM High Voltage Adapter Support, YFF0042-C01	YFF0042-C01

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